





EP5087

THERMALLY CONDUCTIVE EPOXY ADHESIVE

PRODUCT DESCRIPTION

EP5087 is a two-component fast curing thermally conductive adhesive, sealant and potting compound. It is designed to deploy heat in electronic applications, with a measured thermal conductivity of 1.5 W/mK. Suitable for metal, plastics, ceramics and ferrite bonding applications.

• CURING PROPERTIES

Work Life @ 25°C	Gel Time @ 25°C	Full Cure
10 min	@ 25° C 24 hours	
	00 111111	@ 65°C 60 min

• PHYSICAL PROPERTIES

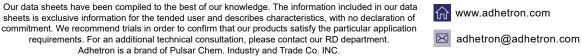
Color	or Gray	
Vicesity	Part A	Part B
Viscosity	Paste	35000 Cps
Specific Gravity	2,35	
Mix ratio (by weight or volume)	1:1	

INSTRUCTIONS FOR USE

Temperature Resistance (°C)	-40 to +150	
Hardness Shore D	75	
Lap Shear Strength (Psi)	1600	
Thermal Conductivity (W/mK)	1,5	
Elongation at Break	25%	
Tg (°C)	56	
Volume Resistivity • 100 V (Ω-cm) • 500 V (Ω-cm)	8.0 x 10 ¹⁴ 6.3 x 10 ¹⁴	
Dielectric Constant 120 Hz 1000 Hz	4.3 4.3	
Dissipation Factor 120 Hz 1000 Hz	0.002 0.002	













EP5087

THERMALLY CONDUCTIVE EPOXY ADHESIVE

• INSTRUCTIONS FOR USE

The surfaces should be free of dust, oil and other dirt in order to optain an optimal efficient bond.

Shelf life: Store in original, unopened containers for 12 months at room temperature The resin of part B might cristalize during storage. This process is reversible by heating (1 hour @ 60°C).

